

# RENESAS SEMICONDUCTOR RELIABILITY REPORT

GROUP : RA2E1  
DEVICE : R7FA2E1XXX  
APPLICATION : Consumer / Industry

Quality Assurance Div.  
Renesas Electronics Corporation

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**Table. Reliability test results (QFP)**

Test Items	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Ta=125 °C, Vccmax, 1000 hrs	0/22	
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 °C, 1000 hrs	0/22	
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 °C, RH=85 %, Vccmax, 1000 hrs	0/22	
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-65 °C to 150 °C , 300 cycles	0/22	
Latch-Up (LU)	JESD78	Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-1000 V, 1 time	0/3	Class: 1C
Electrostatic discharge (ESD-CDM)	JESD22-C101	+/-500V,1time	0/3	Class: C2
Solderability (SD)	J-STD-002	245 °C, 5 s, Solder coverage ≥95 %	0/5	
Resistance to Soldering Heat (PC)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3)	0/22	

\*1) With preconditioning per JESD22-A113, MSL 3

·It is tested to confirm that all the samples are satisfied with an individual product specification.

Note :

Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .

**Table. Reliability test results (QFN)**

Test Items	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Ta=125 °C, Vccmax, 1000 hrs	0/22	
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 °C, 1000 hrs	0/22	
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 °C, RH=85 %, Vccmax, 1000 hrs	0/22	
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-65 °C to 150 °C , 300 cycles	0/22	
Latch-Up (LU)	JESD78	Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-1000 V, 1 time	0/3	Class: 1C
Electrostatic discharge (ESD-CDM)	JESD22-C101	+/-500V,1time	0/3	Class: C2
Solderability (SD)	J-STD-002	245 °C, 5 s, Solder coverage ≥95 %	0/5	
Resistance to Soldering Heat (PC)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3)	0/22	

\*1) With preconditioning per JESD22-A113, MSL 3

·It is tested to confirm that all the samples are satisfied with an individual product specification.

Note :

Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .

**Table. Reliability test results (BGA)**

Test Items	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Ta=125 °C, Vccmax, 1000 hrs	0/22	
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 °C, 1000 hrs	0/22	
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 °C, RH=85 %, Vccmax, 1000 hrs	0/22	
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-55 °C to 125 °C , 500 cycles	0/22	
Latch-Up (LU)	JESD78	Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-1000 V, 1 time	0/3	Class: 1C
Electrostatic discharge (ESD-CDM)	JESD22-C101	+/-500V,1time	0/3	Class: C2
Resistance to Soldering Heat (PC)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3)	0/22	

\*1) With preconditioning per JESD22-A113, MSL 3

·It is tested to confirm that all the samples are satisfied with an individual product specification.

Note :

Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .

**Table. Reliability test results (LGA)**

Test Items	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Ta=125 °C, Vccmax, 1000 hrs	0/22	
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 °C, 1000 hrs	0/22	
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 °C, RH=85 %, Vccmax, 1000 hrs	0/22	
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-55 °C to 125 °C , 500 cycles	0/22	
Latch-Up (LU)	JESD78	Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-1000 V, 1 time	0/3	Class: 1C
Electrostatic discharge (ESD-CDM)	JESD22-C101	+/-500V,1time	0/3	Class: C2
Resistance to Soldering Heat (PC)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3)	0/22	

\*1) With preconditioning per JESD22-A113, MSL 3

·It is tested to confirm that all the samples are satisfied with an individual product specification.

Note :

Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .

The failure rate of the device in an actual use condition can be estimated by the below procedure.

**•Equation for the failure rate estimation ( $\lambda$ )**

$$\lambda = \lambda_b \times \pi T \text{ (FIT)}$$

① Unique failure rate ( $\lambda_b$ )

$$\lambda_b = 4.1 \text{ FIT}$$

Unique failure rate at  $T_a = 55^\circ\text{C}$  using 60 % confidence level.

② Temperature term ( $\pi T$ )

$$\pi T = \exp\{11600 \times E_a \times (1/(273+55) - 1/(273+T_a))\}$$

$E_a$  : Activation energy (eV)

$T_a$  : Ambient temperature ( $^\circ\text{C}$ )

$\pi T$ simplified chart as $E_a = 0.7 \text{ eV}$												
$T_a$ ( $^\circ\text{C}$ )	40	50	55	60	65	70	75	80	85	90	100	110
$\pi T$	0.31	0.68	1	1.45	2.08	2.95	4.15	5.77	7.96	10.88	19.82	34.99

**•MTTF ( Mean Time To Failure )**

$$MTTF = 1/\lambda$$

## Reference about Renesas package code

Package type		Package code *1
Lead type plastic package	QFP	PxQP
Non-lead type plastic package	QFN	PxQN
Grid array type plastic package	BGA	PxBG
	LGA	PxLG

\*1. First four digit

Table. Product list

No	Group	Product part number	Package code	No	Group	Product part number	Package code
1	RA2E1	R7FA2E1A72DBU	PVBG0064L*	51			
2	RA2E1	R7FA2E1A73CBU	PVBG0064L*	52			
3	RA2E1	R7FA2E1A92DBU	PVBG0064L*	53			
4	RA2E1	R7FA2E1A93CBU	PVBG0064L*	54			
5	RA2E1	R7FA2E1A52DFJ	PLQP0032G*	55			
6	RA2E1	R7FA2E1A53CFJ	PLQP0032G*	56			
7	RA2E1	R7FA2E1A72DFJ	PLQP0032G*	57			
8	RA2E1	R7FA2E1A73CFJ	PLQP0032G*	58			
9	RA2E1	R7FA2E1A92DFJ	PLQP0032G*	59			
10	RA2E1	R7FA2E1A93CFJ	PLQP0032G*	60			
11	RA2E1	R7FA2E1A72DFK	PLQP0064G*	61			
12	RA2E1	R7FA2E1A73CFK	PLQP0064G*	62			
13	RA2E1	R7FA2E1A92DFK	PLQP0064G*	63			
14	RA2E1	R7FA2E1A93CFK	PLQP0064G*	64			
15	RA2E1	R7FA2E1A52DFL	PLQP0048K*	65			
16	RA2E1	R7FA2E1A53CFL	PLQP0048K*	66			
17	RA2E1	R7FA2E1A72DFL	PLQP0048K*	67			
18	RA2E1	R7FA2E1A73CFL	PLQP0048K*	68			
19	RA2E1	R7FA2E1A92DFL	PLQP0048K*	69			
20	RA2E1	R7FA2E1A93CFL	PLQP0048K*	70			
21	RA2E1	R7FA2E1A72DFM	PLQP0064K*	71			
22	RA2E1	R7FA2E1A73CFM	PLQP0064K*	72			
23	RA2E1	R7FA2E1A92DFM	PLQP0064K*	73			
24	RA2E1	R7FA2E1A93CFM	PLQP0064K*	74			
25	RA2E1	R7FA2E1A52DLM	PWLG0036K*	75			
26	RA2E1	R7FA2E1A53CLM	PWLG0036K*	76			
27	RA2E1	R7FA2E1A72DLM	PWLG0036K*	77			
28	RA2E1	R7FA2E1A73CLM	PWLG0036K*	78			
29	RA2E1	R7FA2E1A92DLM	PWLG0036K*	79			
30	RA2E1	R7FA2E1A93CLM	PWLG0036K*	80			
31	RA2E1	R7FA2E1A52DNE	PWQN0048K*	81			
32	RA2E1	R7FA2E1A53CNE	PWQN0048K*	82			
33	RA2E1	R7FA2E1A72DNE	PWQN0048K*	83			
34	RA2E1	R7FA2E1A73CNE	PWQN0048K*	84			
35	RA2E1	R7FA2E1A92DNE	PWQN0048K*	85			
36	RA2E1	R7FA2E1A93CNE	PWQN0048K*	86			
37	RA2E1	R7FA2E1A52DNH	PWQN0032K*	87			
38	RA2E1	R7FA2E1A53CNH	PWQN0032K*	88			
39	RA2E1	R7FA2E1A72DNH	PWQN0032K*	89			
40	RA2E1	R7FA2E1A73CNH	PWQN0032K*	90			
41	RA2E1	R7FA2E1A92DNH	PWQN0032K*	91			
42	RA2E1	R7FA2E1A93CNH	PWQN0032K*	92			
43				93			
44				94			
45				95			
46				96			
47				97			
48				98			
49				99			
50				100			